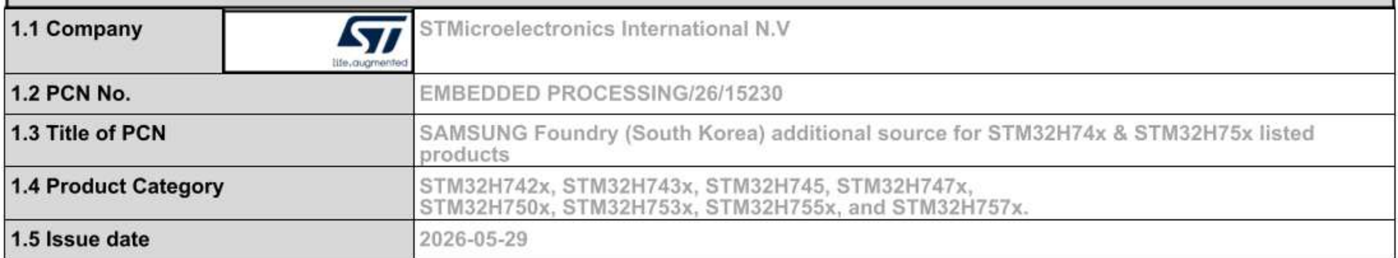
PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company 	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/15230
1.3 Title of PCN	SAMSUNG Foundry (South Korea) additional source for STM32H74x & STM32H75x listed products
1.4 Product Category	STM32H742x, STM32H743x, STM32H745, STM32H747x, STM32H750x, STM32H753x, STM32H755x, and STM32H757x.
1.5 Issue date	2026-05-29

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	
2.1.2 Phone	
2.1.3 Email	
2.2 Change responsibility	
2.2.1 Product Manager	
2.1.2 Marketing Manager	
2.1.3 Quality Manager	

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication (SOP 2617)	ST Crolles (France) HHGrace Wuxi (China) SAMSUNG Foundry (South Korea)

4. Description of change	Old	New
4.1 Description	Front-end source: - ST Crolles 12" (France) - HHGrace Wuxi (China)	Front-end sources: - ST Crolles 12" (France) - HHGrace Wuxi (China) - SAMSUNG Foundry 12" (South Korea) - added source There is no change in the product functionality. Please refer to PCN – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Packaged products : no change.	

5. Reason / motivation for change	
5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose & Automotive Microcontroller division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change	
6.1 Description	Change is visible through diffusion traceability plant, on the marking: - "VQ" for ST Crolles 12" (France) - "Y5" for HHGrace FAB7 (China) - "2E" for HHGrace FAB9 (China) - "LM" for SAMSUNG 12" (South Korea)

7. Timing / schedule	
7.1 Date of qualification results	2026-05-05
7.2 Intended start of delivery	2026-09-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	15230 MDG-GPM-RER2403_PCN15230 V1_450-transfer-to-SF - reliability evaluation report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-05-29

9. Attachments (additional documentations)
15230 Public product.pdf 15230 MDG-GPM-RER2403_PCN15230 V1_450-transfer-to-SF - reliability evaluation report.pdf 15230 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H743BIT6	
	STM32H743VIT6E	
	STM32H750IBT6	
	STM32H750VBT6TR	

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Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : SAMSUNG Foundry (South Korea) additional source for STM32H74x & STM32H75x listed products
PCN Reference : EMBEDDED PROCESSING/26/15230

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H743BGT6	STM32H747XGH6	STM32H742XGH6
STM32H743VGT6	STM32H755ZIT6	STM32H745XGH6
STM32H750ZBT6	STM32H753XIH6	STM32H755XIH3TR
STM32H755XIH3	STM32H755XIH6	STM32H742VGH6
STM32H743VIT6	STM32H743IGK6	STM32H747XIH6
STM32H745BIT6	STM32H757XIH6	STM32H742AGI6
STM32H745BGT6	STM32H743IIT6	STM32H743XGH6
STM32H742VIH6	STM32H745XIH6	STM32H743VIT6TR
STM32H757XIH6A	STM32H750XBH6	STM32H750IBK6
STM32H742AII6	STM32H745IGK6	STM32H750IBT6
STM32H745ZIT6	STM32H745XIH3	STM32H753VIT6
STM32H747BIT6	STM32H745ZGT6	STM32H753IIK6
STM32H745XIH3TR	STM32H742XIH6	STM32H743BIT6
STM32H743IIK6	STM32H747BGT6	STM32H742IGK6
STM32H753XIH6TR	STM32H753BIT6	STM32H755IIK3
STM32H743ZGT6	STM32H747XIH6TR	STM32H743IGT6
STM32H750VBT6	STM32H743ZIT6	STM32H742ZGT6
STM32H742VIT6TR	STM32H743XIH6	STM32H757AII6
STM32H743AII6TR	STM32H755IIT3	STM32H745BIT3
STM32H745ZIT3	STM32H742VGT6TR	STM32H742VGT6
STM32H753AII6	STM32H745IIK3	STM32H745XIH6TR
STM32H742ZIT6	STM32H742IIK6	STM32H743VIH6
STM32H742AGI6TR	STM32H753ZIT6	STM32H742VIT6
STM32H743VIH6TR	STM32H753IIT6	STM32H750VBT6TR
STM32H742IIT6	STM32H747AGI6	STM32H747IGT6
STM32H757IIT6	STM32H742VIH6TR	STM32H743ZIT6TR
STM32H747ZIY6TR	STM32H755IIT6	STM32H755XIH6TR
STM32H747AII6	STM32H745IGT6	STM32H742BIT6
STM32H755BIT3	STM32H757ZIY6TR	STM32H747IIT6
STM32H755IIK6	STM32H743AII6	STM32H742BGT6
STM32H743AGI6	STM32H745IIK6	STM32H743IIK6TR
STM32H753VIH6	STM32H757BIT6	STM32H745IIT6
STM32H755ZIT3	STM32H745IIT3	STM32H755BIT6
STM32H747IIT3	STM32H743VGH6	

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PRODUCT/PROCESS CHANGE NOTIFICATION PCN15230 – Additional information

SAMSUNG Foundry (South Korea) additional source for STM32H74x & STM32H75x listed products

MDRF – General Purpose & Automotive Microcontrollers Division (GPAM)

What are the changes?

SAMSUNG Foundry, an additional diffusion FAB, has been activated to improve our capacity throughput. We will have the possibility to supply the same commercial product, either from Crolles, from HHGrace or from Samsung foundry.

How can the change be seen?

The standard marking fields example for **UFBGA 10X10 176+25** package

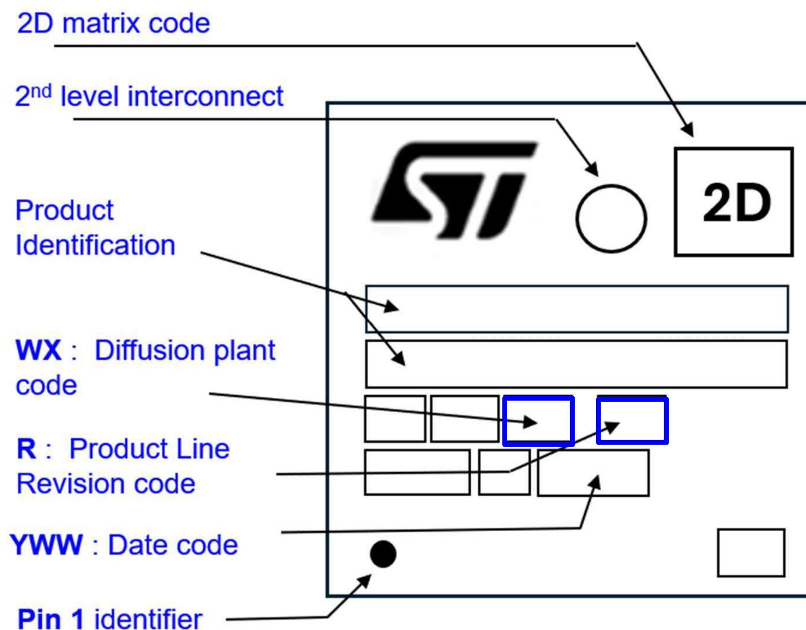

Table_1: Revision code marking field

Marking field		Existing			Additional
		ST Crolles 12" (France)	HHGrace Wuxi (China) Fab7	Fab9	SAMSUNG Foundry (South Korea)
WX	**Revision code**	**VQ**	**Y5**	**2E**	**LM**

Table_2: Package top view marking examples

Package marking examples	ST Crolles 12" (France)	HHGrace Wuxi (China) Fab7	Fab9	SAMSUNG Foundry (South Korea)
UFBGA 10X10 176+25L (ie: STM32H755IIK3)	2D STM32H755IIK 3 VQ V	2D STM32H755IIK 3 Y5 2	2D STM32H755IIK 3 2E 3	2D STM32H755IIK 3 LM 1
LQFP 14x14 100L (ie: STM32H742VIT6)	2D STM32H742VIT 6 VQ V	2D STM32H742VIT 6 Y5 2	2D STM32H742VIT 6 2E 3	2D STM32H742VIT 6 LM 1

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number “**PCN15230**” into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request

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Reliability Report

MDG-GPM-RER2403

CMOSM40 Technology Transfer from CR300 to SF – Die 450

General Information	
Commercial Product	STM32H74x & STM32H75x
Product Line	450X66
Die revision	450 cut 2.2
Product Description	STM32H74x & STM32H75x
Package	TFBGA 14X14 240+25L TFBGA 8x8 100L UFBGA 10x10 176+25L UFBGA 7x7 169L LQFP 14X14 100L LQFP 20x20 144L LQFP 24X24 176L
Silicon Technology	CMOSM40MI
Division	MDRF-GPAM
Reliability Maturity Level	20 -> W29

Traceability	
Diffusion Plant	Samsung Foundry FabS1
Assembly Plant	SC ASE – TAIWAN ATP1 AMKOR – PHILIPPINES ATP3 AMKOR - PHILIPPINES

Reliability Assessment	
Pass	X
Fail	

Release	Date	Author	Function
1.0	05/05/2026	Elsa Le Maitre	GPAM FE Q&R

DOCUMENT ACTORS:

Name	Function	Location	Date
Berengere ROUTIER-SCAPPUCCI	GPAM BE Q&R Manager	ROUSSET	05/05/2026
Dominique GALIANO	Division Q&R Responsible	GRENOBLE	05/05/2026
Pascal NARCHE	Subgroup Quality Manager	ROUSSET	05/05/2026

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RELIABILITY EVALUATION OVERVIEW

- **OBJECTIVE**

The aim of this report is to present results of the reliability evaluation performed for the following products diffused in Samsung Foundry FabS1 plant (M40 technology).

Product	Process or Package	FG	Assembly plant	Diffusion plant
Die 450	TFBGA14x14 240+25L Cu	QC32H747XIH6$28	ASE	Samsung Foundry FabS1
Die 450	LQFP14X14 100L Cu	QC32H743VIT6$28	ASE	Samsung Foundry FabS1

PCN15230 changes are described below:

- Fab ST Crolles 12" (France) diffusing M40 used for STM32H747/743 products will be transferred to Samsung Foundry diffusion Samsung Foundry FabS1 (Korea).
- The design database remains the same. No change in the silicon Die 450 cut2.2 version
- No change in packages supply chain

Qualification is based on standard STMicroelectronics Corporate Procedures for Quality and Reliability, in full compliancy with the JESD-47 international standard.

- **CONCLUSION**

All reliability tests have been completed with positive results. Neither functional nor parametric rejects were detected at final electrical testing.

According to good reliability tests results in line with validated product mission profile and reliability strategy, qualification can be granted for die 450 cut2.2 diffused in Samsung Foundry FabS1 for below packages:

TFBGA14x14 240+25L ASE (Cu wire).

LQFP14x14 100L ASE (cu wire)

The report will be updated with results on additional packages, in Q3’2026.

Refer to Section 3.0 for reliability test results

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1. RELIABILITY STRATEGY

Reliability trials performed as part of this reliability evaluation are in agreement with ST 0061692 specification, in full compliancy with the JESD-47 international standard.

For details on test conditions, generic data used and specifications references, refer to test results summary in section 3.

Die 450 production is transferred to Samsung Foundry FabS1 (Korea). These products are already qualified in internal ST diffusion Fab Crolles 300 (France): RERMCD1401 (450).
The SMPS option for die 450 and 480 in SAMSUNG FOUNDRY is qualified thanks to 480 SMPS die level reliability (MDG-GPM-RER2203 - eSTM40 Technology Transfer from CR300 to SF – Die 480).).

According to “RELIABILITY TESTS AND CRITERIA FOR QUALIFICATION” specification (DMS 0061692), the following qualification strategy has been defined:

- Die Qualification:
  - ✓ 450 cut 2.2: Full reliability exercise on 3 diffusion lots to assess the die (technology driver) in TFBGA14x14 240+25L package.
  - ✓ SMPS configuration assessed within MDG-GPM-RER2203 - eSTM40 Technology Transfer from CR300 to SF – Die 480)
- Package Qualification:
  - ✓ No change in supply chain compared to the one using Fab ST Crolles 12" (France)
  - ✓ Package reliability plan is presented in the following table:

Assembly site	Packages	Device (partial Rawline Code)	Product type	Wire material	Qual	Comments
ASE	TFBGA14x14 240+25L	CV*450	Legacy	Cu	3 Full qual lot	To assess technology transfer
ASE	LQFP14x14 100L	1L*450	Legacy	Cu	1 Full qual lot	na
ASE	LQFP24x24 176L	1T*450	INDUS	Cu	1 Q-lot for CDM + CA	Similarity with 480 SMPS already qualified in this package
ATP1	LQFP20x20 144L	1A*450	Legacy	Cu	1 Q-lot for CDM	Similarity with 480 already qualified in this package Will qualify by similarity LQFP14x14 100L ATP
ATP	UFBGA 10x10 176+25L	MR*450	Legacy	Cu	1 Full qual lot	na
ATP	UFBGA 7x7 169L	OQ*450	Legacy	Cu	1 Q-lot for CDM	Similarity with UFBGA10x10 ATP
ATP	TFBGA14x14 240+25L	CV*450	Legacy	Cu	1 Q-lot for CDM	Similarity with 480 already qualified in this package Will qualify by similarity TFBGA8x8 100L ATP

Note: All product types (Legacy, Indus, GFX) are covered by pkg strategy

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2. PRODUCT OR TEST VEHICLE CHARACTERISTICS

2.1. Generalities

Die 450 is 32-bit microcontroller. Offering a high level of integration, they are suitable for a wide range of applications in consumer, industrial and appliance domains and ready for the Internet of Things (IoT) solutions.

For additional information, refer to products datasheet.

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2.2. Traceability

2.2.1. Wafer Fab Information

Wafer Fab Information	
FAB1	
Wafer fab name / location	SAMSUNG / SAMSUNG FabS1 DIFF
Wafer diameter (inches)	12 inches
Wafer thickness (µm)	775 +/-25 µm
Silicon process technology	CMOSM40MI
Number of masks	51
Die finishing front side (passivation) materials	PSG NITRIDE
Die finishing back side Materials	RAW SILICON
Die area (Stepping die size)	23.230746 mm² (4983, 4662)
Die pad size	Geometry: Rectangular; Open(X,Y): 54.9x54.4 µm
Sawing street width (X,Y) (µm)	72.6 x 72.9 µm
Metal levels/Materials/Thicknesses	see table below

Wire bond pad metal	Composition	Thickness
1	Cu	0.145 µm
2	Cu	0.13 µm
3	Cu	0.13 µm
4	Cu	0.13 µm
5	Cu	0.13 µm
6	Cu	0.85 µm
7	Cu	0.85 µm
8	Ta/Tan/Cu	1.45 µm

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2.2.2. Assembly Information for qualified packages (will be updated upon new packages qualification)

Assembly Information	
Package 1: TFBGA 14X14X1.2 P 0.8 240+25L	
Assembly plant name / location	ASE Taiwan
Pitch (mm)	0.8
Die thickness after back-grinding (µm)	100µm±15µm
Die sawing method	Laser groove + mechanical sawing
Bill of Material elements	
Substrate material/supplier/reference	SUBSTRATE TFBGA 14x14 265L ASE
Balls metallurgy/diameter/supplier	SOLDER BALLS DIAM 350um SACN305
Die attach material/glue/supplier	Tape ABLESTICK ATB-125
Wire bonding material/diameter	CuPd / 0.8mils
Molding compound material/supplier/reference	KYOCERA G1250AAS ULA
Package Moisture Sensitivity Level (JEDEC J-STD020D)	3

Assembly Information	
Package 2: LQFP 14X14X1.2 P 1 100L	
Assembly plant name / location	ASE Taiwan
Pitch (mm)	1
Die thickness after back-grinding (µm)	375±25
Die sawing method	Laser groove + mechanical sawing
Bill of Material elements	
Lead frame/material/reference	LQ14 100L Pure Tin C7025 6.6sq
Lead frame finishing (material)	Sn (e3)
Die attach material/glue/supplier	HITACHI EN4900G
Wire bonding material/diameter	Wire CuPd 0.8 mils
Molding compound material/supplier/reference	MOLDING RESIN SUMITOMO EME-G631SH
Package Moisture Sensitivity Level (JEDEC J-STD020D)	3

2.2.3. Reliability testing information

Reliability Testing Information	
Reliability laboratory name / location	Grenoble Rel Lab, Rousset MDG Rel Lab, Shenzhen Rel Lab

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3. TEST RESULTS SUMMARY

If the test plan is not in line with the one planned initially, include necessary explanation.

3.1. Lot information

Lot #	Diffusion Lot / Wafer ID	Die Revision (Cut)	Trace Code	Raw Line	Package	Note
Lot 1	LM320014 / NZVAR #05	450 (cut2.2)	AA409017	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Die level reliability
Lot 2	LM402052 / NZVFY #10	450 (cut2.2)	AA415002	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Die level reliability
Lot 3	NZV8W #14	450 (cut2.2)	AA416001	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Die level reliability
Lot 4	LM402052 / NZVFY #19	450 (cut2.2)	AA415002	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Die level reliability
Lot 5	NZV8W #18	450 (cut2.2)	AA416001	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Die level reliability
Lot 6	LM320014 / NZVAR #24	450 (cut2.2)	AA414009	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Package level reliability
Lot 7	LM402052 / NZVFY #21	450 (cut2.2)	AA415002	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Package level reliability
Lot 8	NZV8W #21	450 (cut2.2)	AA416001	28CV*450QCX1	TFBGA 14X14X1.2 P 0.8 240 25L	Package level reliability
Lot 9	LM431028	450 (cut2.2)	AA014513	201L*450QCX1	LQFP 14X14X1.1 P 1 100L	Package level reliability

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3.2. Test plan and results summary

ACCELERATED LIFETIME SIMULATION TESTS

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
EDR	JESD22-A117	10kcy EW @ 125°C then Storage HTB 150°C – Duration 1500H	3	77	231	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77	NA
EDR	JESD22-A117	10kcy EW @ 25°C then Storage HTB 150°C – Duration 168h	3	77	231	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77	NA
EDR	JESD22-A117	10kcy EW @ -40°C then Storage HTB 150°C – Duration 168H	3	77	231	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77	NA
ELFR	JESD22-A108 JESD74	Ta=125°C Duration= 48hrs 3V6	3	800	2400	Lot 1 : 0/800 Lot 4 : 0/800 Lot 5 : 0/800	NA
HTOL	JESD22 A108	Ta=125°C Duration= 1200H 3V6	3	77	231	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77	NA

ACCELERATED ENVIRONMENT STRESS TESTS

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
PC	JSTD 020 JESD22-A113	24h bake@125°C, MSL3 192h/30°C/60%RH 3x Reflow simulation Peak Reflow Temp=260°C	4	308	1232	Lot 6: 0/308 Lot 7: 0/308 Lot 8: 0/308 Lot 9: 0/308	NA
HTSL	JESD22-A103	Ta=150°C Duration= 1000hrs ☑ After PC	4	77	308	Lot 6: 0/77 Lot 7: 0/77 Lot 8: 0/77 Lot 9: 0/77	NA
TC	JESD22-A104	Ta= -65 to 150°C Cyc= 500 cy ☑ After PC	4	77	308	Lot 6: 0/77 Lot 7: 0/77 Lot 8: 0/77 Lot 9: 0/77	NA
THB	JESD22-A101	Ta=85%HR/85°C/VDD max Duration= 1000hrs ☑ After PC	4	77	308	Lot 6: 0/77 Lot 7: 0/77 Lot 8: 0/77 Lot 9: 0/77	NA
UHAST	JESD22-A118	Ta=130°C/85%RH Duration= 96hrs ☑ After PC	4	77	308	Lot 6: 0/77 Lot 7: 0/77 Lot 8: 0/77 Lot 9: 0/77	NA

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Electrical Verification Tests

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
CDM	JS-002	Voltage= 250V, class C1	5	3	15	Lot 1: 0/3 Lot 2: 0/3 Lot 3: 0/3 Lot 6: 0/3 Lot 9: 0/3	NA
HBM	ANSI/JEDEC JS-001	Ta=25°C 1.5kV, Class 1C	3	3	9	Lot 1: 0/3 Lot 2: 0/3 Lot 3: 0/3	NA
LU	JESD78	140°C Tj	3	3	9	Lot 1: 0/3 Lot 2: 0/3 Lot 3: 0/3	NA

PACKAGE ASSEMBLY INTEGRITY TESTS

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
CA	ST internal specifications	Construction analysis including BS/PT	2	50	100	Lot 6: 0/50 Lot 9: 0/50	SHZ – CA_24_00213 SHZ - CA_25_00614

Note: Test method revision reference is the one active at the date of reliability trial execution.

4. APPLICABLE AND REFERENCE DOCUMENTS

Reference	Short description
JESD47	Stress-Test-Driven Qualification of Integrated Circuits
SOP2.4.4	Record Management Procedure
SOP2.6.2	Internal Change Management
SOP2.6.7	Finished Good Maturity Management
SOP2.6.9	Package & Process Maturity Management in BE
SOP2.6.11	Program Management for Product Development
SOP2.6.17	Management of Manufacturing Transfers
SOP2.6.19	Front-End Technology Platform Development and Qualification
DMS 0061692	Reliability Tests and Criteria for Product Qualification
JEDEC JS-001	Electrostatic discharge (ESD) sensitivity testing human body model (HBM)
JEDEC JS-002	Electrostatic discharge (ESD) sensitivity testing charge device model (CDM)
JESD78	IC Latch-up test
JESD22-A103	High Temperature Storage Life
JESD22-A104	Temperature cycling

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JESD22-A108	Temperature, Bias and Operating Life
JESD22-A101	Temperature Humidity Bias
JESD22-A113	Preconditioning of non-hermetic surface mount devices prior to reliability testing
JESD22-A117	Endurance and Data retention
JESD22-A118	Unbiased Highly Accelerated temperature & humidity Stress Test
J-STD-020	Moisture/reflow sensitivity classification for non-hermetic solid state surface mount devices

5. GLOSSARY

HTOL	High Temperature Operating Life
EDR	Endurance and Data Retention
ELFR	Early Failure Rate
ESD HBM	Electrostatic discharge - human body model
ESD - CDM	Electrostatic Discharge - Charged device model
LU	Latch-up
CA	Construction analysis
HTSL	High temperature storage life
PC	Preconditioning
TC	Temperature Cycling
THB	Temperature Humidity Bias
UHAST	Unbiased HAST (Highly Accelerated Stress Test)
DMS	ST Advanced Documentation Controlled system/ Documentation Management system
BS/PT	Ball Shear/ Pull Test

6. REVISION HISTORY

Release	Date	Description
1.0	05/05/2026	Initial release

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